



**SUMMARY REPORT
ON
International Wireless
Symposium**

**14 - 18 April 2013
Beijing/China**

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**On Behalf
MALAYSIAN TECHNICAL STANDARDS
FORUM BHD**

TABLE OF CONTENTS

- 1. Abstract**
- 2. List of Participants**
- 3. Introduction /Background**
- 4. Agendas/Topics**
- 5. Findings**
- 6. Conclusion**
- 7. Acknowledgement**

1. Abstract

The objective of this paper is to report on the inaugural International Wireless Symposium as a new microwave conference to be held annually in China. The focus of the symposium is “everything that is wireless” encompassing academia, wireless industry, regulators and service providers on issues within the wireless community. The symposium is intended to attract attendees and exhibitors from all part of wireless community, and to become a major global wireless event.

2. List of Participant

The representative from Malaysian Technical Standard Forum is:

1. En. Najib Fadil Mohd Bisri (WG WT/MTSFB)

3. Introduction / Background

The International Wireless Symposium (IWS) is a new microwave conference sponsored by the IEEE Microwave Theory and Techniques Society debuting in 2013. It will be an international event that will be held annually in China.

The focus is “everything that is wireless” , including phones, Bluetooth, Zigbee, data, and a myriad of hardware, as well as regulatory and provider issues within the wireless community. Patterned after the very famous MTT-S International Microwave Symposium (IMS), the IWS will have a technical conference and a commercial exhibition. Because the market place for wireless technology, devices, and service is immense, the IWS will grow to be similar to the IMS.

This year over 160 papers scheduled to be presented in multiple parallel tracks, with over a hundred industrial and other exhibitors (a few were canceled). The papers presented at IWS will be archived in IEEE Xplore. IWS will rotate between several locations in China, but will be an international event with participants from all over the world. The exhibition will include manufacturers and service providers from worldwide, with marketing happening in both directions: both into, and out from China. The IWS is intended to attract attendees and exhibitors from all parts of the wireless community, and will become a major global wireless event.

4. Agendas/Topics

SUNDAY	0830 - 1230 Workshops & Short Courses		1330 - 1730 Workshops & Short Courses		14 April 2013	
	WS1: THz Material Growth, Device Fabrication and Modeling					
	WS2: Measurement Developments for Future Wireless Technologies					
			WS3: Wireless Chip Development and Entrepreneurial Efforts in China			
			WS4: Recent Advances in mmW, Submmwave and THz MMICs for Novel System Design			
	WS5: Power Amplifiers for Next Generation Cellular Communication (Full Day)		WS5: Power Amplifiers for Next Generation Cellular Communication (Full Day)			
WS6: Wireless Power Transfer Technologies (Full Day)		WS6: Wireless Power Transfer Technologies (Full Day)				
		SC3: Microwave Measurement Techniques in a Wireless Transceiver Design Cycle				
Registration: 0700-1800						
MONDAY	0800-0940 Technical Sessions		1200-1300 Panel Session	1330-1510 Technical Sessions	1540-1720 Technical Sessions	15 April 2013
	M01B: Wireless Communication and Networking Techniques		Wireless Power Transfer: An Old Technology Sparks a Modern Revolution	M03A: Technologies for Advanced Wireless Devices (FOCUS SESSION)	M04B: Novel Low Noise Circuits and Design	
	M01C: Filters I				M04C: Filters II	
	M01D: Low Power, Low Noise, and Ultrawideband Transceivers				M04D: Printed Antennas	
Registration: 0700-1800 • IWS Plenary Session: 1000-1200 • Student Paper Competition Poster Session: 1730-1900 • IWS Welcome Reception: 1730-1900						
TUESDAY	0800-0940 Technical Sessions	1010-1150 Technical Sessions	1200-1300 Panel Session	1330-1510 Technical Sessions	1540-1720 Technical Sessions	16 April 2013
	TU1A: Filters III	TU2A: Wireless Data and Power Transceivers for Biomedical Applications (FOCUS SESSION)	Radiation Testing in Wireless Communication: Challenges and Solutions	TU3A: Control Devices	TU4A: Emerging Wireless Device and Design Techniques (FOCUS SESSION)	
	TU1B: Wireless Energy Transfer and Harvesting			TU3B: Emerging Wireless Devices, Techniques and Systems		
	TU1C: High Efficiency and Wideband Power Amplifiers			TU3C: Novel Transceivers for Radars and Location Identification		
	TU1D: Millimeter-wave and THz Techniques and Systems			TU3D: Antennas for Wireless Communications		
Registration: 0700-1800 • Exhibition: 1000-1700 • Industrial Forum: 1000-1700 • Interactive Forum: 1330-1630 (TUP1: Wireless Device, Circuit and System Components) Chapter Chair's Meeting: 1800-2130						
WEDNESDAY	0800-0940 Technical Sessions	1010-1150 Technical Sessions	1330-1510 Technical Sessions	1540-1720 Technical Sessions	17 April 2013	
		WE2A: Cognitive Radio Communications and Networks (FOCUS SESSION)		WE4A: RF Nanotechnologies for Next-Generation Wireless Communication (FOCUS SESSION)		
	WE1B: Frequency Synthesis, Power Combiners, and Behavioral Modeling of RF Power Amplifiers	SPECIAL SESSION: How to Write a Paper for IEEE MTT-S Journals and Navigate the Review Process	WE3B: Building Blocks for RF Integrated Front-end			
	WE1C: Antennas and Transmission Lines		WE3C: Couplers and Dividers			
	WE1D: Millimeter-wave and UWB Antennas		WE3D: Array Antennas			
Registration: 0700-1800 • Exhibition: 1000-1700 • Industrial Forum: 1000-1700 • Special Session: 1010-1130 • Interactive Forum: 1330-1630 (WEP2: Integrated Circuits and Antennas for Wireless Communication) • Closing Ceremony: 1730-1845 • IWS Banquet: 1900-2130						
THURSDAY	0830 - 1230 Workshops & Short Courses		1330 - 1730 Workshops & Short Courses		18 April 2013	
	WS7: THz Packaging Integration Technologies					
	WS8: Advanced Modeling Techniques for Carbon-Based RF and THz Structures					
	WS9: E-Band Technologies and Applications					
			WS10: Computational Multi-physics Methods and Applications for Advanced RF Micro/Nanoelectronic Devices and Interconnects			
	WS12: Digital Techniques for Power Amplifiers Linearity and Efficiency Enhancement (Full Day)		WS12: Digital Techniques for Power Amplifiers Linearity and Efficiency Enhancement (Full Day)			
SC4: Implantable and Wearable Wireless Medical Devices and Systems		SC5: The Time-Domain Transform and its Applications				
Registration: 0700-1600 • Exhibition: 1000-1500 • Industrial Forum: 1000-1200						

5. Findings

IWS 2013 technical program features core technologies for the next generation wireless networks and systems by presenting up-to-the-last minute achievements in the areas of, but not limited to, Short-Range, Broadband, and Green Wireless Systems & Standards, Modulation, Coding & Signal Processing, Wireless Energy Transmission & Harvesting, Smart Grid, as well as their enabling RF, Microwave, Millimeter-wave & THz Technologies including Front-End Electronics, Antennas, Signal Generation & Power Amplification, Transceiver Techniques, Active/Passive Electronics & Components, and Antennas.

The Technical Program Committee (TPC) received 355 papers including 20 invited from 35 countries (5 continents) worldwide, indicating the vitality of this new conference and promise for further future growth. Based on TPC recommendation, 161 regular and invited papers presented scheduled for 24 podium sessions and 2 poster sessions over 3 days.

Illustrious guests were invited to talk on Advanced Wireless Devices, Wireless Data and Power Transceivers for Biomedical Applications, Emerging Wireless Devices and Design Techniques, Cognitive Radio Communications and Networks, and RF Nanotechnologies for Next Generation Wireless Communications.

6. Conclusion

The IWS 2013 successfully provided a platform for academics, wireless professionals, regulators and service providers to share ideas on wireless technology study and how wireless technologies being applied to improve the quality of life.

7. Acknowledgement

My deepest thanks to SKMM for their trust and in allowing me to attend the inaugural International Wireless Forum in Beijing, China.

I express my thanks to MTSFB for extending their support in providing international exposure to working group members.

I would also like to thank TM which encourage and support my involvement in the working group activities for the benefit of the industry.